

SN54107, SN54LS107A, SN74107, SN74LS107A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

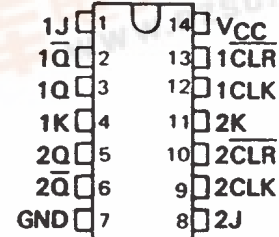
The '107 contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '107 is a positive pulse-triggered flip-flop. The J-K input data is loaded into the master while the clock is high and transferred to the slave and the outputs on the high-to-low clock transistion. For these devices the J and K inputs must be stable while the clock is high.

The 'LS107A contain two independent negative-edge-triggered flip-flops. The J and K inputs must be stable prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the \bar{Q} output high.

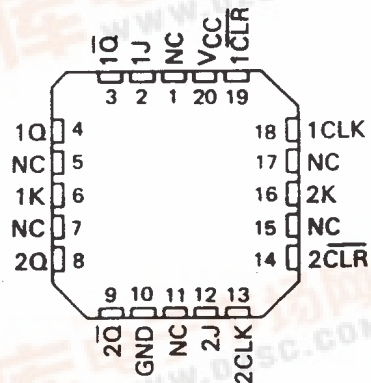
The SN54107 and the SN54LS107A are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74107 and the SN74LS107A are characterized for operation from 0°C to 70°C .

SN54107, SN54LS107A . . . J PACKAGE
SN74107 . . . N PACKAGE
SN74LS107A . . . D OR N PACKAGE

(TOP VIEW)



SN54LS107A . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

'107
FUNCTION TABLE

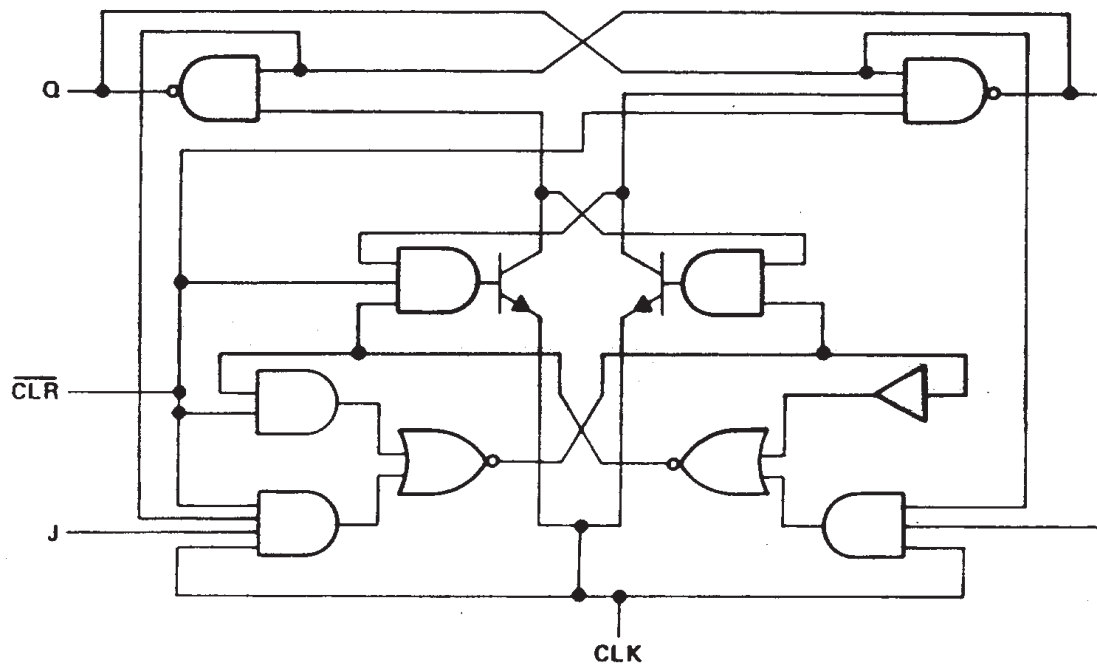
INPUTS				OUTPUTS	
$\bar{\text{CLR}}$	CLK	J	K	Q	\bar{Q}
L	X	X	X	L	H
H	\downarrow	L	L	Q_0	\bar{Q}_0
H	\downarrow	H	L	H	L
H	\downarrow	L	H	L	H
H	\downarrow	H	H	TOGGLE	TOGGLE

'LS107A
FUNCTION TABLE

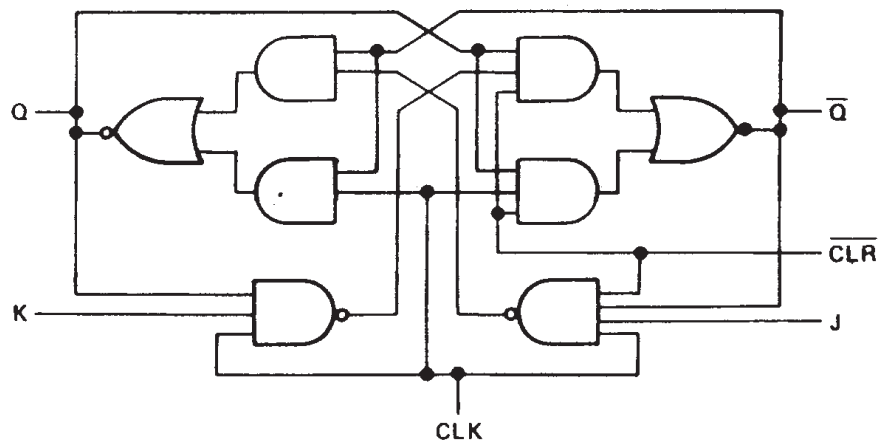
INPUTS				OUTPUTS	
$\bar{\text{CLR}}$	CLK	J	K	Q	\bar{Q}
L	X	X	X	L	H
H	\downarrow	L	L	Q_0	\bar{Q}_0
H	\downarrow	H	L	H	L
H	\downarrow	L	H	L	H
H	\downarrow	H	H	TOGGLE	TOGGLE
H	H	X	X	Q_0	\bar{Q}_0

SN54107, SN54LS107A,
SN74107, SN74LS107A
DUAL J-K FLIP-FLOPS WITH CLEAR
SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

logic diagrams (positive logic)

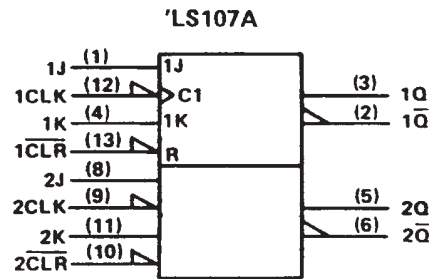
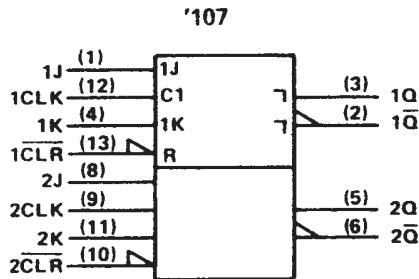


'LS107A



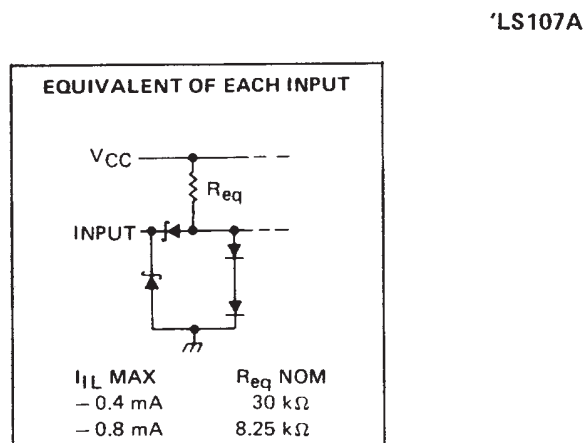
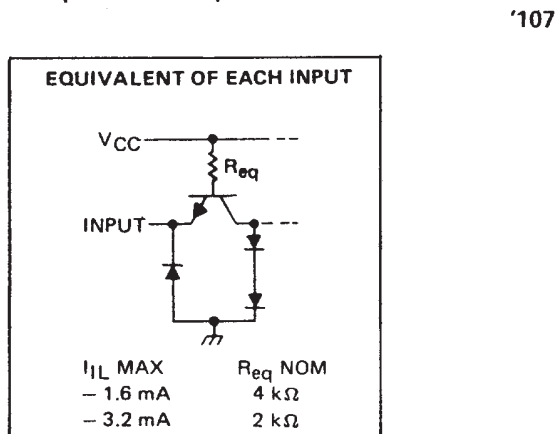
SN54107, SN54LS107A,
SN74107, SN74LS107A
DUAL J-K FLIP-FLOPS WITH CLEAR
SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

logic symbols†



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, and N packages.

schematic of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage: '107	5.5 V
'LS107A	7 V
Operating free-air temperature range: SN54'	– 55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	– 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54107, SN74107

DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

		SN54107			SN74107			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			– 0.4			– 0.4	mA
I_{OL}	Low-level output current			16			16	mA
t_w	Pulse duration		CLK high	20		20		ns
			CLK low	47		47		
			CLR low	25		25		
t_{su}	Input setup time before CLK†	0			0			ns
t_h	Input hold time-data after CLK†	0			0			ns
T_A	Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54107			SN74107			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		$V_{CC} = \text{MIN}, I_I = -12 \text{ mA}$				– 1.5			– 1.5	V
V_{OH}		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -0.4 \text{ mA}$		2.4	3.4		2.4	3.4		V
V_{OL}		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 16 \text{ mA}$			0.2	0.4		0.2	0.4	V
I_I		$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$				1			1	mA
I_{IH}	J or K	$V_{CC} = \text{MAX}, V_I = 2.4 \text{ V}$				40			40	μA
	All other					80			80	
I_{IL}	J or K	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$				– 1.6			– 1.6	mA
	All other					– 3.2			– 3.2	
$I_{OS}§$		$V_{CC} = \text{MAX}$		– 20		– 57	– 18		– 57	mA
$I_{CC}¶$		$V_{CC} = \text{MAX},$ See Note 2			10	20		10	20	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$.

§Not more than one output should be shorted at a time.

¶Average per flip-flop.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \bar{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ \text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
f_{max}			$R_L = 400 \Omega, C_L = 15 \text{ pF}$		15	20		MHz
t_{PLH}	$\overline{\text{CLR}}$	\bar{Q}				16	25	ns
t_{PHL}		Q				25	40	ns
t_{PLH}	CLK	Q or \bar{Q}				16	25	ns
t_{PHL}		Q or \bar{Q}				25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN54LS107A, SN74LS107A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS036 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

			SN54LS107A			SN74LS107A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.7			0.8	V
I _{OH}	High-level output current				− 0.4			− 0.4	mA
I _{OL}	Low-level output current				4			8	mA
f _{clock}	Clock frequency		0		30	0		30	MHz
t _w	Pulse duration	CLK high	20			20			ns
		CLR low	25			25			
t _{su}	Setup time before CLK ↓	data high or low	20			20			ns
		CLR inactive	25			25			
t _h	Hold time-data after CLK ↓		0			0			ns
T _A	Operating free-air temperature		− 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS107A		SN74LS107A		UNIT
				MIN	TYP‡	MAX	MIN	
V _{IK}		V _{CC} = MIN, I _I = – 18 mA			– 1.5		– 1.5	V
V _{OH}		V _{CC} = MIN, I _{OH} = – 0.4 mA	V _{IH} = 2 V, V _{IL} = MAX,	2.5	3.4		2.7 3.4	V
V _{OL}		V _{CC} = MIN, I _{OL} = 4 mA	V _{IL} = MAX, V _{IH} = 2 V,		0.25 0.4		0.25 0.4	V
		V _{CC} = MIN, I _{OL} = 8 mA	V _{IL} = MAX, V _{IH} = 2 V,				0.35 0.5	
I _I	J or K	V _{CC} = MAX, V _I = 7 V				0.1	0.1	mA
	CLR					0.3	0.3	
	CLK					0.4	0.4	
I _{IH}	J or K	V _{CC} = MAX, V _I = 2.7 V				20	20	μA
	CLR					60	60	
	CLK					80	80	
I _{IL}	J or K	V _{CC} = MAX, V _I = 0.4 V				– 0.4	– 0.4	mA
	CLR or CLK					– 0.8	– 0.8	
I _{OS} §		V _{CC} = MAX, See Note 4		– 20	– 100	– 20	– 100	mA
I _{CC} (Total)		V _{CC} = MAX, See Note 2			4 6		4 6	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \bar{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}			R _L = 2 kΩ, C _L = 15 pF	30	45		MHz
t _{PLH}	CLR or CLK	Q or Q̄			15	20	ns
t _{PHL}					15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/00203BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74107N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74107N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74107N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74107N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS107AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS107AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS107AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS107AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS107ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS107ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS107ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS107ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

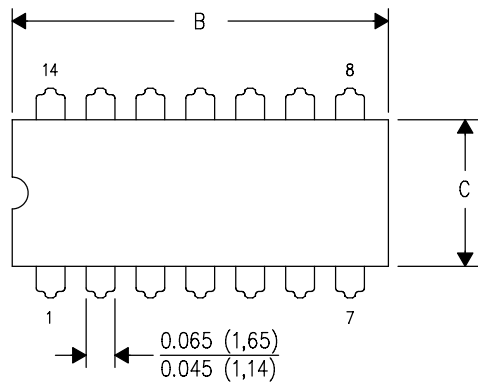
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

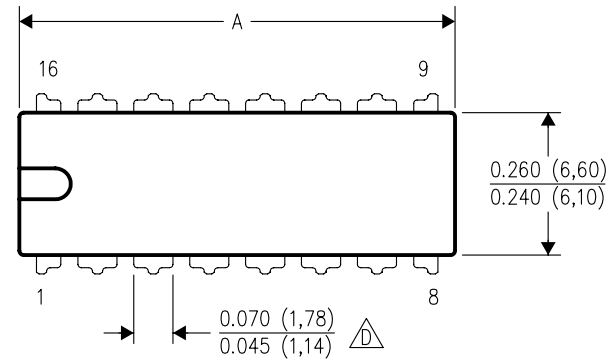
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

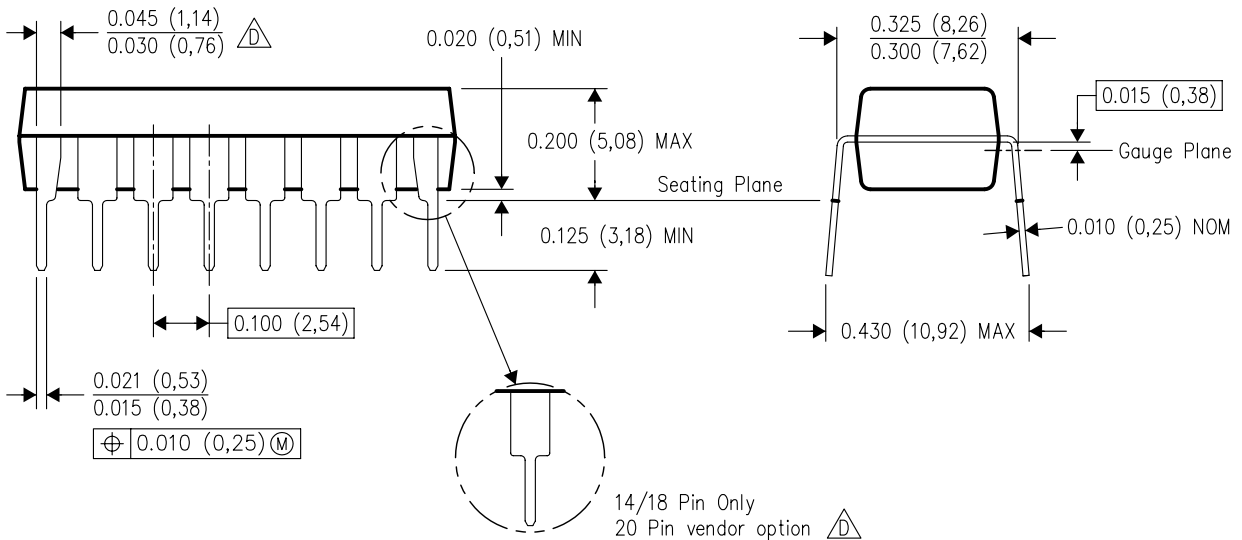
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



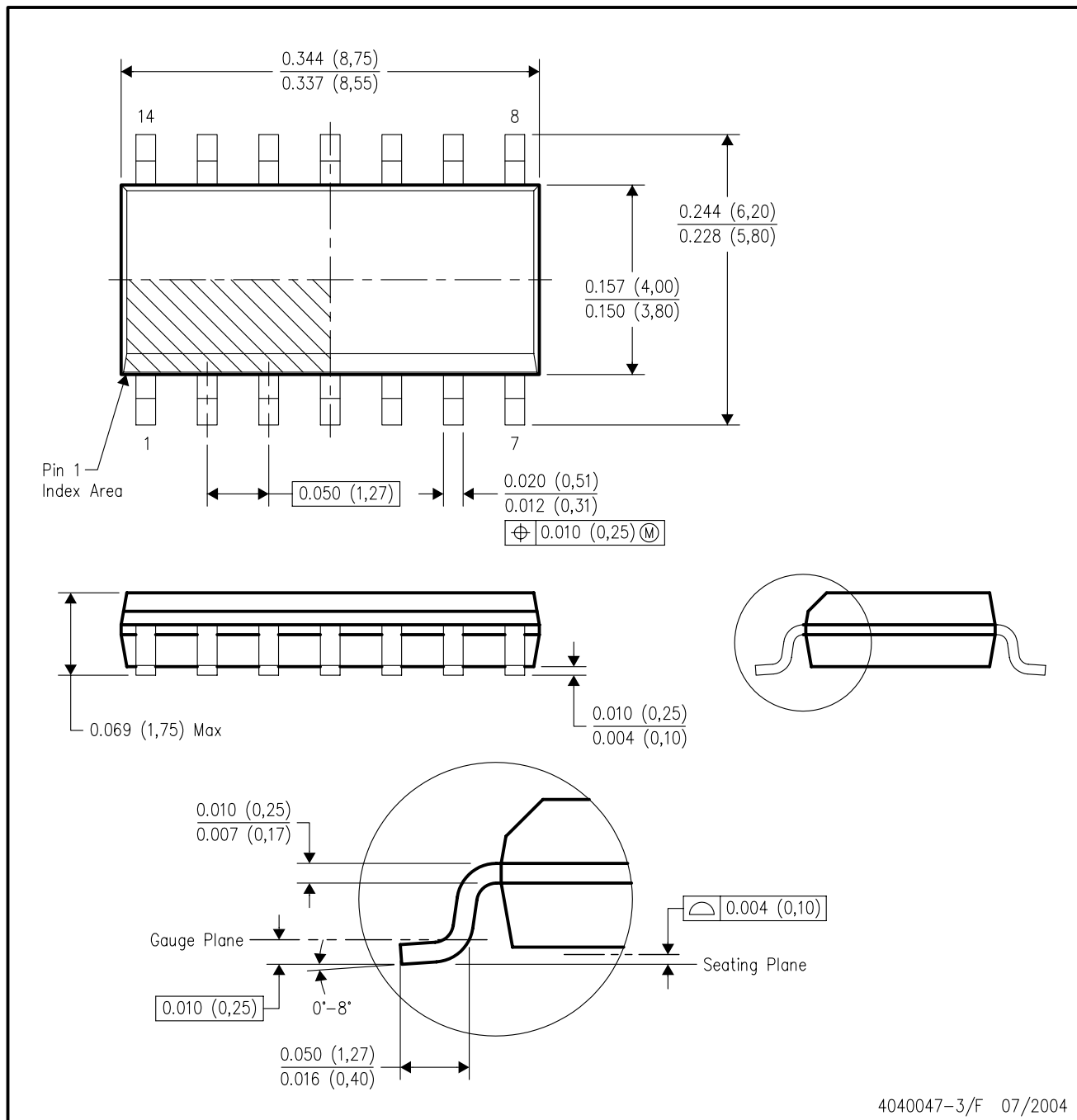
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

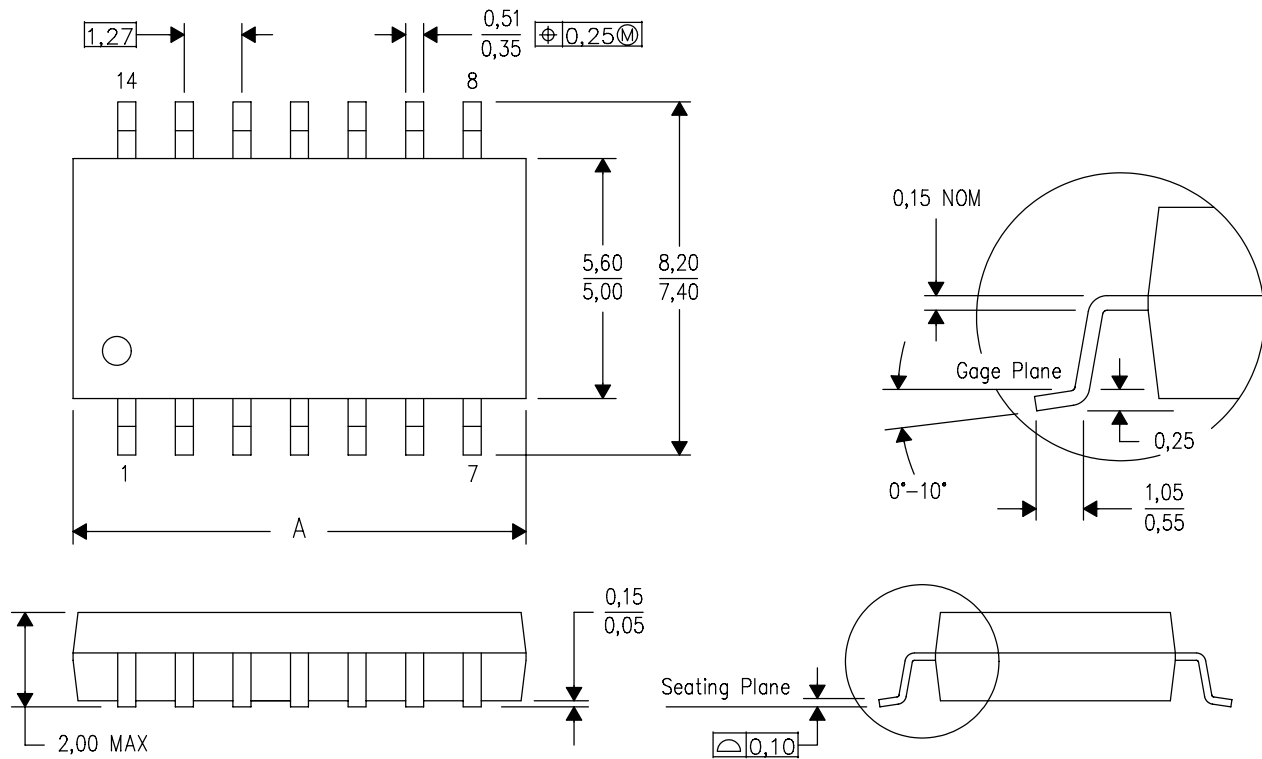
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265